Flip-Chips・NCSP Integrated Package 倒装芯片・NCSP集成封装 Bicolor NCSP Integrated COBs **双色NCSP集成COB光**源

Main Applications: 主要应用领域:

✓ long-distance searching and spot lighting for stage, studio, photography, landmarks, architectural, facade illumination, military and police search lights etc.

长距离探照与聚光照明,适用于舞台,演艺,摄影,影视,地标,建筑, 景观,军警探照等

- ✓ directional projection and beam lighting with small angle for projection, light beam, dyeing, pattern, audience, business, hotel, museum, etc.
 小角度方向性投射类照明,适用于投射,光束,染色,图案,观众,商 业,酒店,博物馆等
- ✓ intelligent color-mixing lighting 智能混色照明
- ✓ over broader CCT range with higher Ra for lighting of high-end business, stage, studio, photography etc.
 宽色温范围高显指照明,适用于高端商业、舞台、影视、摄影等

<u>C1364</u>



Main Parameters	Typical Values
Voltage (V)	54
Current (mA)	6300 in total
Max. Power(W) ^{Note}	441
LES (mm)	26.5
CCT (K) / Ra	2400-2600 / >95 7500-8100 / >95
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H084

Note: The maximum power only for reference and related to the heat dissipation power of the radiator, the thermal resistance between the radiator and the light source and the ambient temperature.

Main	High Power Bicolor NCSP Integrated COB;
Features	NCSP Mosaic Layout for Excellent Color Uniformity;
	Flip Chips with No Gold Wires for High Integration & Good Reliability;
	Customizing Other Power, LES, Color Combination, CCT and Ra;

Applicable to Directional Intelligent Lighting with Wide CCT Variation at High Ra $_{\circ}$



[Data in table, photos & diagrams for reference only]

<u>C1363</u>



Main Parameters	Typical Values
Voltage (V)	54
Current (mA)	9450 in total
Max. Power(W) ^{Note}	661
LES (mm)	32
CCT (K) / Ra	2400-2600 / >95 7500-8100 / >95
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H086

Note: The maximum power only for reference and related to the heat dissipation power of the radiator, the thermal resistance between the radiator and the light source and the ambient temperature.

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